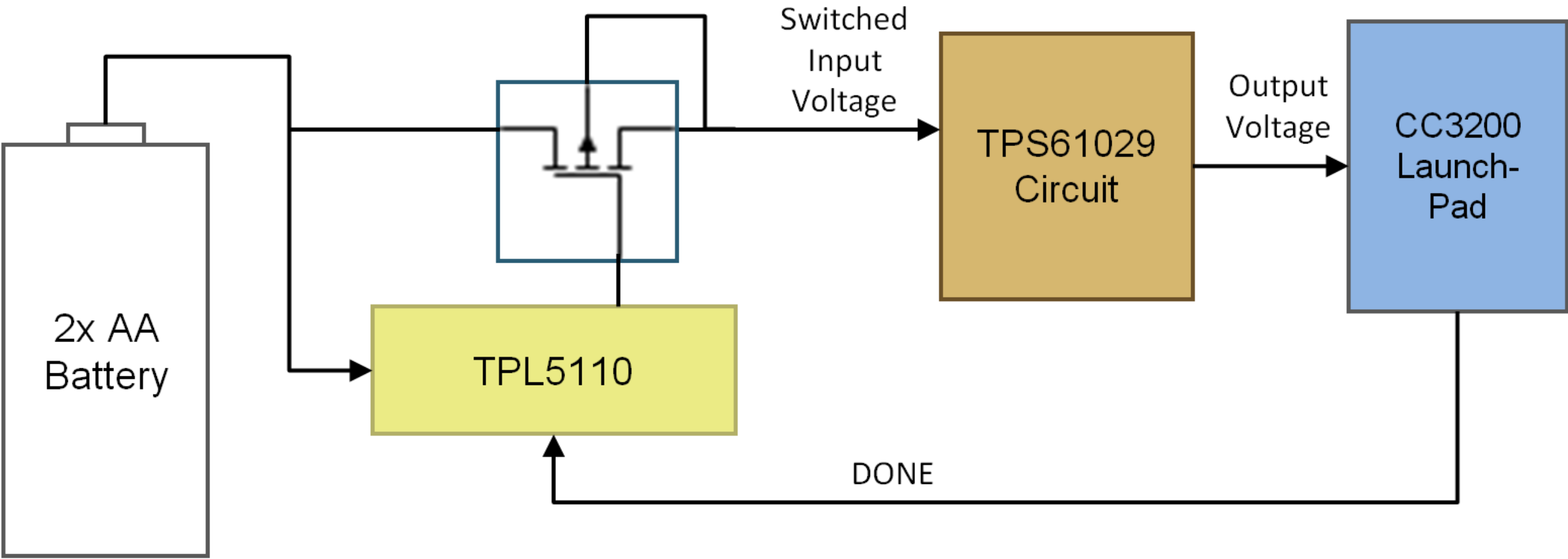
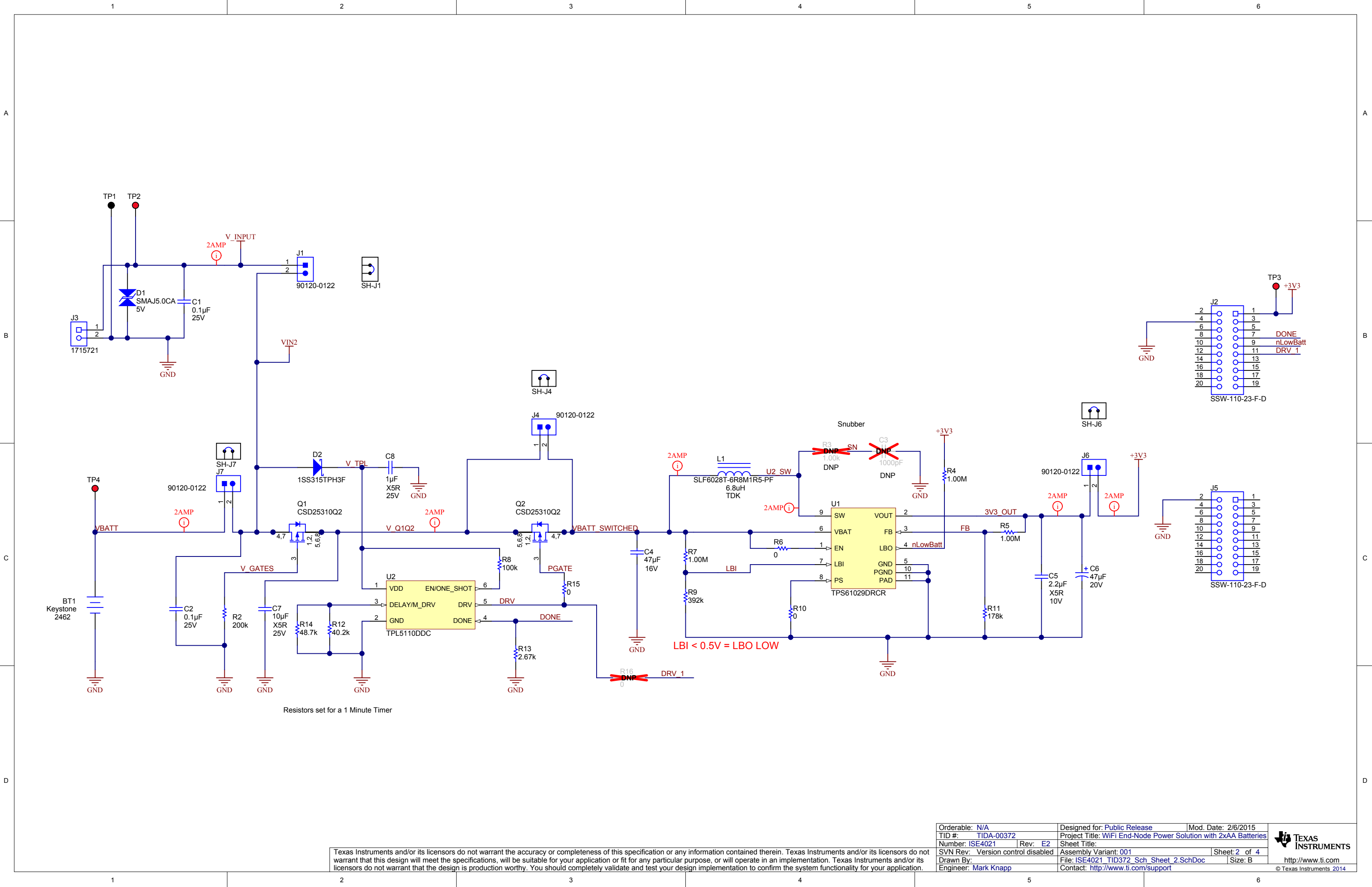


Revision History	
Revision	Notes
E2	Change C4 to 47uF, Add D2 and C8, Change Power Connection on U2 from D2, Move DONE, nLowBatt and DRV_1 to J2

Block Diagram





Resistors set for a 1 Minute Timer

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Orderable: N/A		Designed for: Public Release		Mod. Date: 2/6/2015	
TID #: TIDA-00372		Project Title: WiFi End-Node Power Solution with 2x AA Batteries		Sheet Title:	
Number: ISE4021		Rev: E2		Assembly Variant: 001	
SVN Rev: Version control disabled		File: ISE4021_TID372_Sch_Sheet_2.SchDoc		Sheet: 2 of 4	
Drawn By:		Size: B		Contact: http://www.ti.com/support	
Engineer: Mark Knapp					



PCB Number: ISE4021

PCB Rev: E2

PCB

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Pb-Free Symbol

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Label Table	
Variant	Label Text
001	Serial number

ZZ1

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ4

Assembly Note

Place SH-J1 on J1, SH-J4 on J4, SH-J6 on J6 and SH-J7 on J7 (pins 1-2).

ZZ5

Assembly Note

J2 and J5 must NOT have the lead ends trimmed off.

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